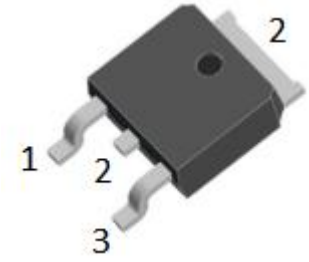
Technical Data
Data Sheet N1317, Rev. A

MBRD10200 SCHOTTKY RECTIFIER

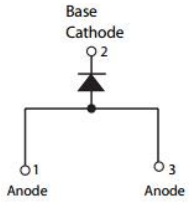


DPAK

Features

- 175℃ T_J operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Terminals finish: 100% Pure Tin
- This is a Pb − Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection
- Battery charging

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	-	200	V
Average Rectified Forward Current	$I_{F\ (AV)}$	50% duty cycle @Tc=105°C, rectangular wave form	10	A
Peak One Cycle Non-Repetitive Surge Current	I_{FSM}	8.3ms, Half Sine pulse	150	A

Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop*	V_{F1}	@ 10A, Pulse, T_J = 25 °C	0.85	0.90	V
	V_{F2}	@ 10A, Pulse, T_J = 125 °C	0.75	0.85	V
Reverse Current *	I_{R1}	@V_R = rated V_R, T_J = 25 °C	0.0002	1.0	mA
	I_{R2}	@V_R = rated V_R, T_J = 125 °C	0.03	50	mA
Junction Capacitance	C_T	@V_R = 5.0V, T_C = 25 °C f_{SIG} = 1MHz	120	300	pF
Series Inductance	L_S	Measured lead to lead 5 mm from package body	8.0	-	nH
Voltage Rate of Change	dv/dt	-	-	10,000	V/μs

* Pulse width < 300 μs, duty cycle < 2%

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Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	-	-55 to +175	°C
Storage Temperature	T_{stg}	-	-55 to +175	°C
Typical Thermal Resistance Junction to Case	$R_{\theta JC}$	-	6	°C/W
Approximate Weight	wt	-	0.39	g
Case Style	DPAK			

Ratings and Characteristics Curves

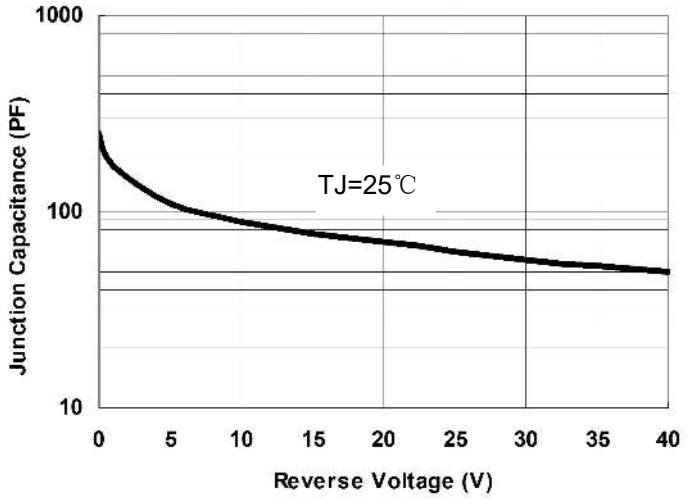

Fig.1-Typical Junction Capacitance

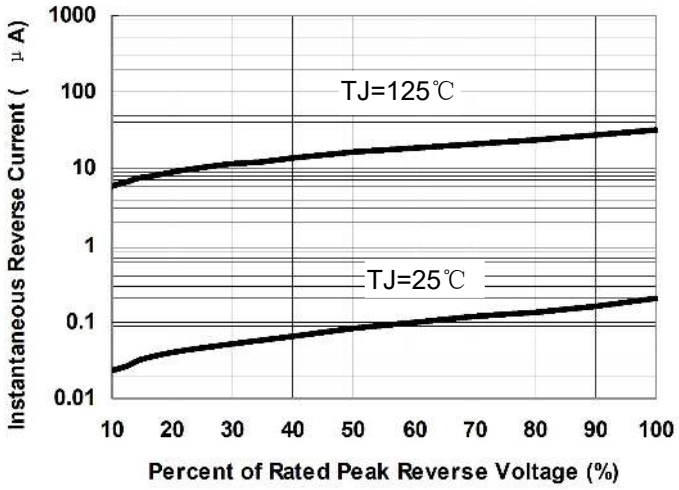

Fig.2-Typical Reverse Characteristics

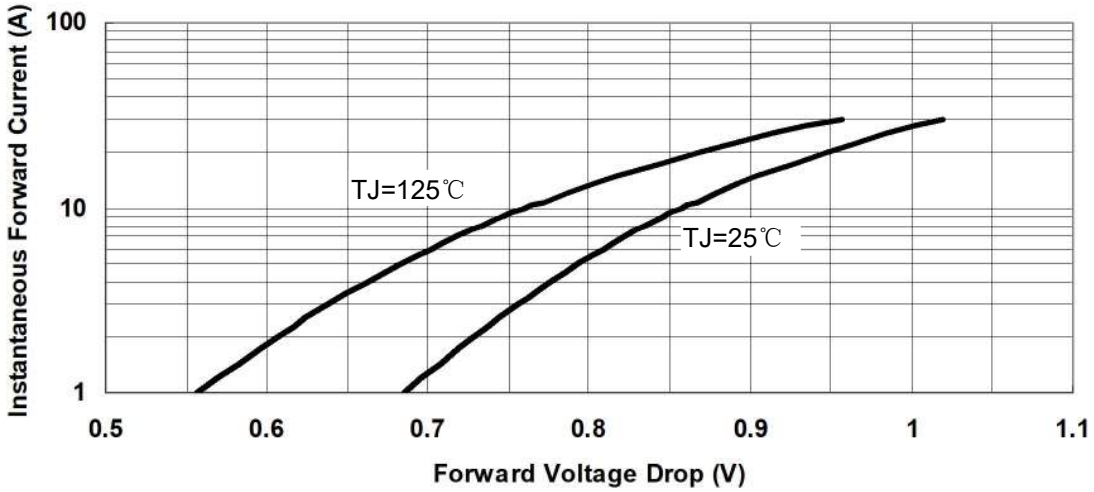

Fig.3-Typical Instantaneous Forward Voltage Characteristics

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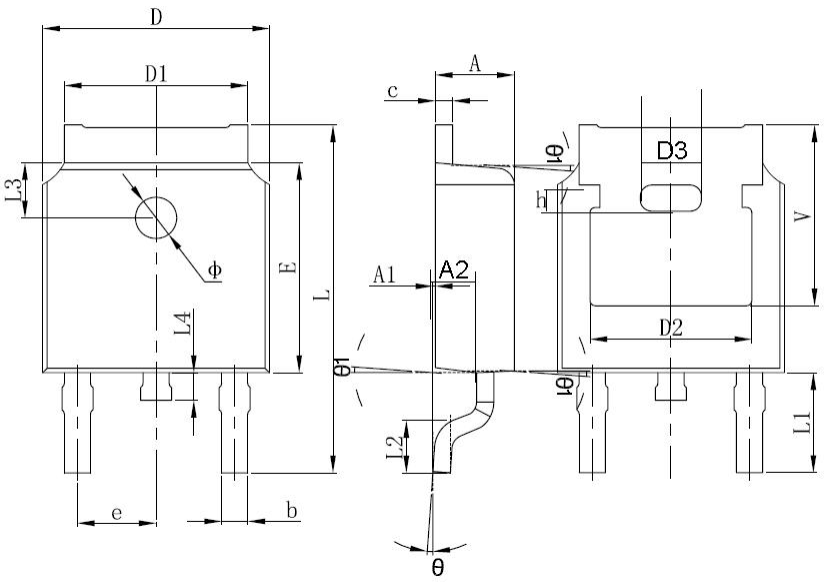
Mechanical Dimensions DPAK



SYMBOL	Dimensions in millimeters		
	Min.	Typ.	Max.
A	2.18	-	2.39
A1	-	-	0.13
b	0.64	-	0.89
c	0.46	-	0.89
D	6.35	-	6.73
D2	4.32	-	-
E	5.97	6.10	6.22
e		2.29BSC	
L	9.40	-	10.41
L2	1.40	1.52	1.78
L4	-	-	1.02
Θ	0°	-	10°
V	5.21	-	-

Ordering Information

Device	Package	Shipping
MBRD10200	DPAK (Pb-Free)	2500pcs / reel
MBRD10200TR	DPAK (Pb-Free)	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

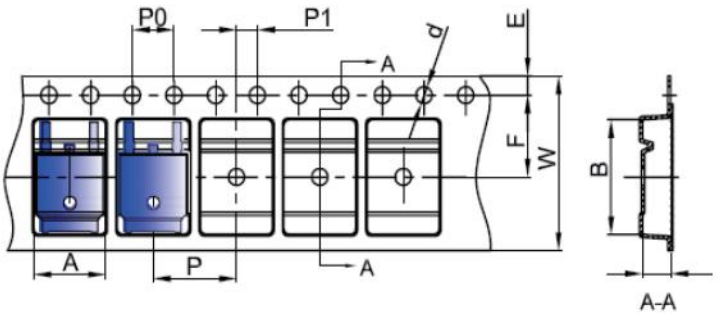
Marking Diagram

Where XXXXX is YYWWL

MBRD10200 = Part Name
SSG = SSG
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Carrier Tape Specification DPAK



SYMBOL	Millimeters	
	Min.	Max.
A	6.80	7.00
B	10.40	10.60
C	2.60	2.80
d	Φ1.45	Φ1.65
E	1.65	1.85
F	7.40	7.60
P0	3.90	4.10
P	7.90	8.10
P1	1.90	2.10
W	15.90	16.30

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